PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MASAYUKI ASAI	04/06/2015
KOICHI HONDA	04/03/2015
MAMORU UMEMOTO	04/06/2015
KAZUYUKI OKUDA	04/03/2015

RECEIVING PARTY DATA

Name:	HITACHI KOKUSAI ELECTRIC INC.
Street Address:	14-1, SOTOKANDA 4-CHOME
City:	CHIYODA-KU, TOKYO
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14667691

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	CO-F03577-06
NAME OF SUBMITTER:	SHELDON J. MOSS
SIGNATURE:	/Sheldon J. Moss/
DATE SIGNED:	05/08/2015
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 2
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DECLARATION AND ASSIGNMENT	Docket Number CO-F03577-06

This Declaration and Assignment is made and entered into by the undersigned parties (the "Inventor(s)"), as of the execution date(s) written below. The assignment effected hereby is made to HITACHI KOKUSAI ELECTRIC INC of Tokyo, Japan, whose mailing address is 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-8980 Japan (the "Assignee").

I/We, the Inventor(s), each declare and agree as follows:

1. Declaration. I believe that I am the original sole inventor, or an original joint inventor, of at least one invention that is disclosed and claimed in the United States Patent Application entitled SUBSTRATE PROCESSING APPARATUS AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD, which is further identified below (the "Application"):

☐ The Application Attached Hereto

☒ The Application Having U.S. Serial No. 14/667,691
and a filing date of March 25, 2015

The Application was made, or authorized to be made, by me. I hereby acknowledge that any willful false statement made in the above declaration is punishable under 18 U.S.C. 1001 by fine, by imprisonment of not more than five (5) years, or both.

2. Assignment. In consideration of the sum of 10,000 Japanese Yen (¥ 10,000), and for other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, and intending to be legally bound hereby, I do hereby assign and transfer all of my right, title and interest, in all countries, in and to (i) the Application, (ii) any and all divisional, continuation, continuation-in-part, reissue or other applications related to the Application or to any patent issued thereon ("Related Applications"), (iii) all inventions and improvements disclosed in the Application and Related Applications, including (without limitation) embodiments not specifically described therein, and (iv) all patents that may be granted on such inventions and improvements, including (without limitation) all patents issued on the Application and Related Applications, to the Assignee. The foregoing (i) - (iv) shall be held and enjoyed by the Assignee for the sole use and benefit of the Assignee, and its successors and assigns, as fully and entirely as the same would have been held by me had this assignment and sale not been made. I request and authorize the Commissioner of Patents and Trademarks to issue any and all United States patents granted on the Application and Related Applications, to the Assignee for the full term thereof, including any extensions. I agree to perform any and all acts reasonably requested by the Assignee, at the Assignee's expense, related to securing, maintaining and enforcing such patents.

I/We, the Inventor(s) acknowledge that I/we have been advised and given opportunity to seek separate legal counsel regarding this Declaration and Assignment.

AGREED AND ACCEPTED:

INVENTOR
By: Masayuki Asai Date: April 6, 2015

Name: Masayuki ASAI City: Toyama, JAPAN

INVENTOR
By: Koichi Honda Date: April 3, 2015

Name: Koichi HONDA City: Toyama, JAPAN

INVENTOR
By: Mamoru Umemoto Date: April 6, 2015

Name: Mamoru UMEMOTO City: Toyama, JAPAN

INVENTOR
By: Kazuyuki Okuda Date: Aprill 3, 2015

Name: Kazuyuki OKUDA City: Toyama, JAPAN